#### CLAIMS

What is claimed is:

1. A layered heater comprising:

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length and a thickness,

wherein the thickness varies along the length of the resistive circuit pattern for a variable watt density.

- The layered heater according to Claim 1, wherein the resistive circuit pattern further comprises a spacing that is constant.
- 3. The layered heater according to Claim 1, wherein the resistive circuit pattern further comprises a spacing that is variable.
- 4. The layered heater according to Claim 1, wherein the resistive circuit pattern further comprises a width that is constant.
- 5. The layered heater according to Claim 1, wherein the resistive circuit pattern further comprises a width that is variable.
- 6. The layered heater according to Claim 1, wherein the layered heater is selected from a group consisting of thick film, thin film, thermal spray, and sol-gel.
- 7. The layered heater according to Claim 1, wherein the resistive circuit pattern is selected from a group consisting of series, parallel, and series-parallel.
- 8. The layered heater according to Claim 1, wherein the variable thickness is continuous.
- 9. The layered heater according to Claim 1, wherein the variable thickness is non-continuous.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a width,

wherein a thickness of the resistive circuit pattern varies across the width of the resistive circuit pattern for a variable watt density.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern comprising a material having a variable composition, wherein the resistive circuit pattern comprises a variable watt density.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length, a width, and a thickness,

wherein the width and the thickness vary along the length of the resistive circuit pattern for a variable watt density.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length, a width, a spacing, and a thickness,

wherein the width, spacing, and thickness vary along the length of the resistive circuit pattern for a variable watt density.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length, a spacing, and a thickness,

wherein the spacing and the thickness vary along the length of the resistive circuit pattern for a variable watt density.

a dielectric layer;

a resistive layer formed on the dielectric layer, the resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length and a thickness; and

a protective layer formed on the resistive layer,

wherein the thickness of the resistive circuit pattern varies along the length of the resistive circuit pattern for a variable watt density.

a substrate;

a dielectric layer formed on the substrate;

a resistive layer formed on the dielectric layer, the resistive layer comprising a resistive circuit pattern, the resistive circuit pattern defining a length and a thickness; and

a protective layer formed on the resistive layer,

wherein the thickness of the resistive circuit pattern varies along the length of the circuit pattern for a variable watt density.

17. A resistive circuit pattern for use in a layered heater, the resistive circuit pattern defining a variable thickness.

at least one resistive layer comprising a resistive circuit pattern, the resistive circuit defining a variable thickness.

19. The layered heater according to Claim 18 further comprising a plurality of resistive layers.

- 20. A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
  - (a) dispensing a conductive ink at a rate onto a surface; and
- (b) varying the dispensing rate of the conductive ink to form a variable thickness resistive circuit pattern.

- 21. A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
  - (a) dispensing a conductive ink at a rate onto a surface; and
- (b) varying a feed speed of the substrate relative to the dispensing of conductive ink to form a variable thickness resistive circuit pattern.

- 22. A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
  - (a) dispensing a conductive ink at a rate onto a surface;
  - (b) varying the dispensing rate of the conductive ink; and
- (c) varying a feed speed of the substrate relative to the dispensing of conductive ink,

wherein a variable thickness resistive circuit pattern is produced.

- 23. A method of forming a resistive circuit pattern of a layered heater, the method comprising the steps of:
- (a) applying a volume of conductive ink onto a surface to form a trace; and
  - (b) applying an additional volume of conductive ink onto the trace, wherein a variable thickness resistive circuit pattern is produced.
- 24. The method according to Claim 23, wherein the volumes of conductive ink are applied by a layered process selected from the group consisting of thick film, thin film, thermal spraying, and sol-gel.
- 25. The method according to Claim 23, wherein the volumes of conductive ink are applied using precision pen writing equipment.
- 26. The method according to Claim 23, wherein the volumes of conductive ink are applied using a silk screening process.

27. A layered heater comprising a means for varying the watt density of a resistive circuit pattern.